- Member of the Texas Instruments Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- Outputs Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

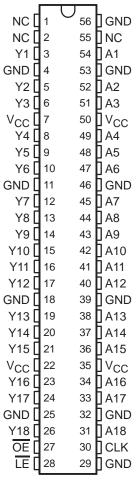
description

This 18-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (\overline{LE}) input is low. The A data is latched if the clock (CLK) input is held at a high or low logic level. If \overline{LE} is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC - No internal connection

The outputs, which are designed to sink up to 12 mA, include equivalent 26- Ω resistors to reduce overshoot and undershoot.

The SN74ALVC162834 is characterized for operation from -40°C to 85°C.



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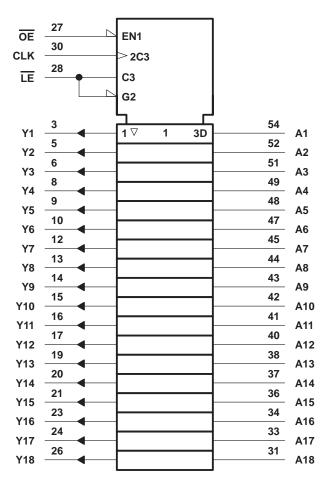


FUNCTION TABLE

	INP	OUTPUT		
OE	LE	CLK	Α	Y
Н	Х	Х	Χ	Z
L	L	Χ	L	L
L	L	Χ	Н	Н
L	Н	\uparrow	L	L
L	Н	\uparrow	Н	Н
L	Н	Н	Χ	Y ₀ †
L	Н	L	Χ	Y ₀ ‡

TOutput level before the indicated steady-state input conditions were established, provided that CLK is high before LE goes high

logic symbol§

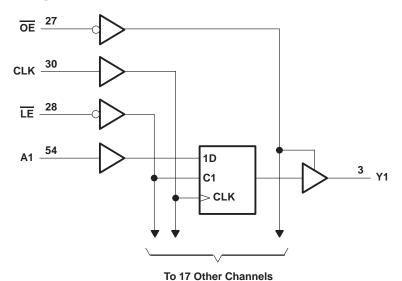


 $[\]$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



[‡] Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)		–0.5 V to 4.6 V
Output voltage range, VO (see Notes 1 and 2)		0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)		–50 mA
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, IO		±50 mA
Continuous current through each V _{CC} or GND		±100 mA
Package thermal impedance, θ _{JA} (see Note 3)	: DGG package	81°C/W
	DGV package	86°C/W
	DL package	74°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



SN74ALVC162834 **18-BIT UNIVERSAL BUS DRIVER** WITH 3-STATE OUTPUTS SCES172A – DECEMBER 1998 – REVISED FEBRUARY 1999

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}			
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ _I	Input voltage		0	VCC	V	
VO	Output voltage		0	VCC	V	
		V _{CC} = 1.65 V		-2		
lou	High-level output current	V _{CC} = 2.3 V		-6	mA	
ЮН		V _{CC} = 2.7 V		-8	IIIA	
		V _{CC} = 3 V		-12		
		V _{CC} = 1.65 V		2		
la.	Low-level output current	V _{CC} = 2.3 V		6	^	
lOL	Low-level output current	$V_{CC} = 2.7 \text{ V}$		8	mA	
		V _{CC} = 3 V		12		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	VCC	MIN	TYP [†]	MAX	UNIT
		$I_{OH} = -100 \mu\text{A}$	1.65 V to 3.6 V	V _{CC} -0.	.2		
		$I_{OH} = -2 \text{ mA}$	1.65 V	1.2			
		$I_{OH} = -4 \text{ mA}$	2.3 V	1.9			
Vон		lou - 6 mA	2.3 V	1.7			V
		IOH = -6 mA	3 V	2.4			
		$I_{OH} = -8 \text{ mA}$	2.7 V	2			
		$I_{OH} = -12 \text{ mA}$	3 V	2			
V _{OL}		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	
		I _{OL} = 2 mA	1.65 V			0.45	V
		I _{OL} = 4 mA	2.3 V			0.4	
		la. 6 mA	2.3 V			0.55	
		IOL = 6 mA	3 V			0.55	
		I _{OL} = 8 mA	2.7 V			0.6	
		I _{OL} = 12 mA	3 V			0.8	
П		V _I = V _{CC} or GND	3.6 V			±5	μΑ
loz		$V_O = V_{CC}$ or GND	3.6 V			±10	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			40	μΑ
Δlcc		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
<u> </u>	Control inputs	V. V CND	227		4		
Ci	Data inputs	V _I = V _{CC} or GND	3.3 V		5.5		pF
Со	Outputs	$V_O = V_{CC}$ or GND	3.3 V		7		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

				V _{CC} =	1.8 V	V _{CC} =	2.5 V 2 V	VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				‡		150		150		150	MHz
	Pulse duration	LE low		‡		3.3		3.3		3.3		200
t _W	Puise duration	CLK high or low		‡		3.3		3.3		3.3		ns
	Data before CLK↑		‡		2.1		2.1		1.7			
t _{su}	t _{Su} Setup time	Bata hatana I E ↑	CLK high	‡		2.3		2.3		1.9		ns
		Data before LE↑	CLK low	‡		1.9		1.9		1.5		
		Data after CLK↑		‡		0.6		0.6		0.7		
t _h Hol	Hold time	Data after LE↑	CLK high or low	‡	·	0.8	·	0.8		0.9		ns

[‡] This information was not available at the time of publication.



SN74ALVC162834 18-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC =	1.8 V	V _{CC} =	2.5 V 2 V	VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(IIVFOT)	(OUTFUT)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		150		150		150		MHz
	А			†	1	5.2		5	1	4.2	
t _{pd}	LE	Y		†	1.3	6		6.8	1.3	5.8	ns
	CLK			†	1.4	6.8		6.1	1.4	5.4	
t _{en}	ŌĒ	Y		†	1.4	6.3		6.5	1.5	5.9	ns
t _{dis}	ŌĒ	Y		†	1	4.4		5.2	1.8	5	ns

[†] This information was not available at the time of publication.

switching characteristics from 0°C to 65°C , C_{L} = 50 pF

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1	UNIT	
	(INFOT)	(001F01)	MIN	MAX	
	А		1.4	3.9	
t _{pd}	LE	Y	1.8	5.5	ns
	CLK		1.8	5.2	

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CO	ONDITIONS	V _{CC} = 1.8 V V _{CC} = 2.5 V V _{CC} =		V _{CC} = 3.3 V	UNIT
PARAMETER		TEST CONDITIONS		TYP	TYP	TYP	UNIT	
<u> </u>	Power dissipation	Outputs enabled	C. 0	f = 10 MHz	†	38	41	ρF
C _{pd}	capacitance	Outputs disabled	$C_L = 0$,	I = 10 MHZ	†	13	15	PΓ

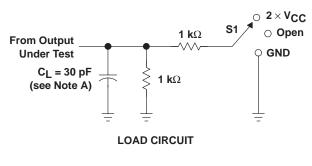
[†] This information was not available at the time of publication.



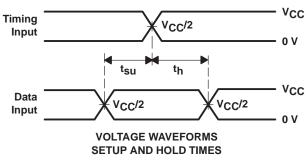
VCC

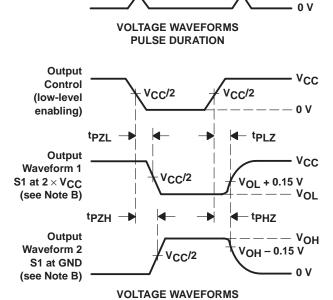
V_{CC}/2

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.8 V



TEST	S1
t _{pd}	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND

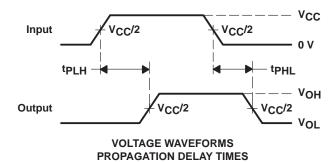




ENABLE AND DISABLE TIMES

V_{CC}/2

Input

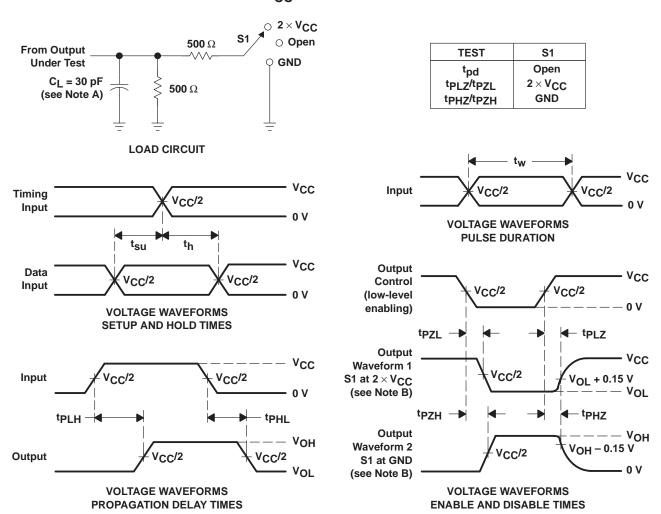


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$



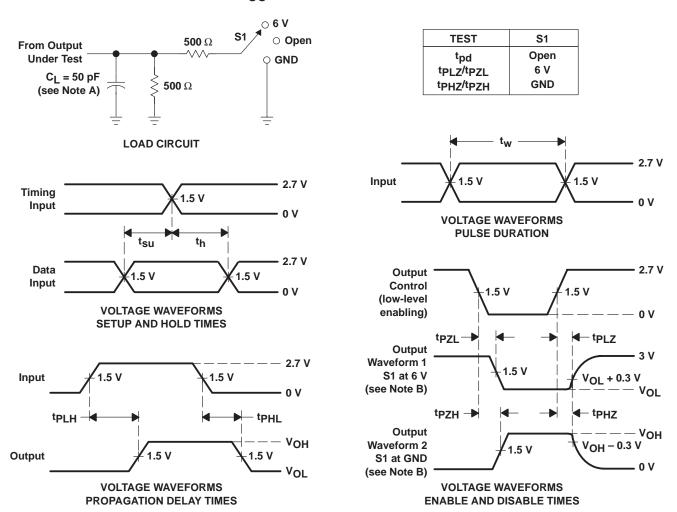
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2.5 \text{ ns.}$
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

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